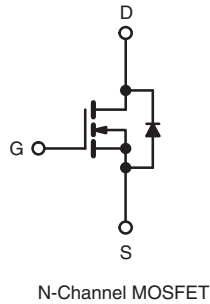
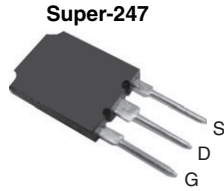


## Power MOSFET



### FEATURES

- Low gate charge  $Q_g$  results in simple drive requirement
- Improved gate, avalanche and dynamic  $dV/dt$  ruggedness
- Fully characterized capacitance and avalanche voltage and current
- Enhanced body diode  $dV/dt$  capability
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



### PRODUCT SUMMARY

$V_{DS}$ (V)	600	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = 10\text{ V}$	0.110
$Q_g$ (Max.) (nC)	330	
$Q_{gs}$ (nC)	84	
$Q_{gd}$ (nC)	150	
Configuration	Single	

### APPLICATIONS

- Hard switching primary or PFC switch
- Switch mode power supply (SMPS)
- Uninterruptible power supply
- High speed power switching
- Motor drive

### ORDERING INFORMATION

Package	Super-247
Lead (Pb)-free and halogen-free	SiHFPS40N60K-GE3

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-source voltage	$V_{DS}$	600	V
Gate-source voltage	$V_{GS}$	$\pm 30$	
Continuous drain current	$V_{GS}$ at 10 V	$T_C = 25\text{ }^\circ\text{C}$	A
		$T_C = 100\text{ }^\circ\text{C}$	
Pulsed drain current <sup>a</sup>	$I_{DM}$	160	
Linear derating factor		4.5	W/ $^\circ\text{C}$
Single pulse avalanche energy <sup>b</sup>	$E_{AS}$	600	mJ
Repetitive avalanche current <sup>a</sup>	$I_{AR}$	40	A
Repetitive avalanche energy <sup>a</sup>	$E_{AR}$	57	mJ
Maximum power dissipation	$T_C = 25\text{ }^\circ\text{C}$	$P_D$	W
Peak diode recovery $dV/dt$ <sup>c</sup>	$dV/dt$	7.5	V/ns
Operating junction and storage temperature range	$T_J, T_{stg}$	- 55 to + 150	$^\circ\text{C}$
Soldering recommendations (peak temperature)	for 10 s	300 <sup>d</sup>	

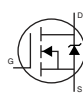
#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- Starting  $T_J = 25\text{ }^\circ\text{C}$ ,  $L = 0.84\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 38\text{ A}$ ,  $dV/dt = 5.5\text{ V/ns}$  (see fig. 12a)
- $I_{SD} \leq 38\text{ A}$ ,  $dI/dt \leq 150\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^\circ\text{C}$
- 1.6 mm from case

### THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	$R_{thJA}$	-	40	$^\circ\text{C}/\text{W}$
Case-to-sink, flat, greased surface	$R_{thCS}$	0.24	-	
Maximum junction-to-case (drain)	$R_{thJC}$	-	0.22	

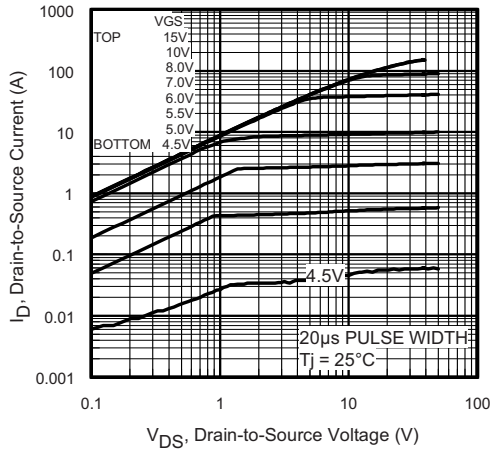


SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
<b>Static</b>							
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	600	-	-	V	
V <sub>DS</sub> temperature coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	Reference to 25 °C, I <sub>D</sub> = 1 mA	-	0.63	-	V/°C	
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	3.0	-	5.0	V	
Gate-source leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 30 V	-	-	± 100	nA	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V	-	-	50	μA	
		V <sub>DS</sub> = 480 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	250		
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 24 A <sup>b</sup>	-	0.110	0.130	Ω	
Forward transconductance	g <sub>fs</sub>	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 24 A <sup>b</sup>	21	-	-	S	
<b>Dynamic</b>							
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1.0 MHz, see fig. 5	-	7970	-	pF	
Output capacitance	C <sub>oss</sub>		-	750	-		
Reverse transfer capacitance	C <sub>rss</sub>		-	75	-		
Output capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 1.0 V, f = 1.0 MHz	-	9440	-	
Effective output capacitance	C <sub>oss eff.</sub>		V <sub>DS</sub> = 480 V, f = 1.0 MHz	-	200	-	
Total gate charge	Q <sub>g</sub>		V <sub>DS</sub> = 0 V to 480 V <sup>c</sup>	-	260	-	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 38 A, V <sub>DS</sub> = 480 V, see fig. 6 and 13 <sup>b</sup>	-	-	330	nC
Gate-drain charge	Q <sub>gd</sub>			-	-	84	
Turn-on delay time	t <sub>d(on)</sub>			-	-	150	
Rise time	t <sub>r</sub>	V <sub>GS</sub> = 10 V	V <sub>DD</sub> = 300 V, I <sub>D</sub> = 38 A, R <sub>G</sub> = 4.3 Ω, see fig. 10 <sup>b</sup>	-	47	-	ns
Turn-off delay time	t <sub>d(off)</sub>			-	110	-	
Fall time	t <sub>f</sub>			-	97	-	
<b>Drain-source body diode characteristics</b>							
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	40	A	
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>		-	-	160		
Body diode voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 38 A, V <sub>GS</sub> = 0 V <sup>b</sup>	-	-	1.5	V	
Body diode reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 38 A, di/dt = 100 A/μs	-	630	950	ns
		T <sub>J</sub> = 125 °C		-	730	1090	
Body diode reverse recovery charge	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	14	20	μC
		T <sub>J</sub> = 125 °C		-	17	25	
Body diode recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C	-	39	58	A	
Forward turn-on time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and L <sub>D</sub> )					

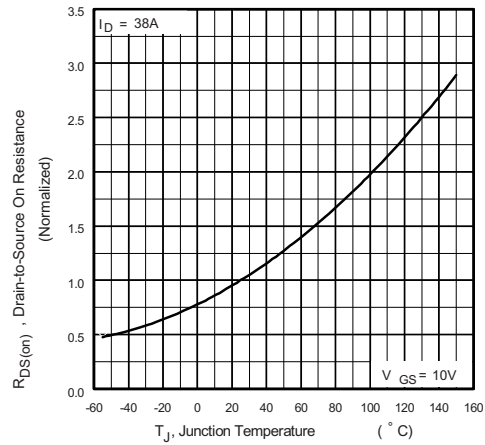
**Notes**

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %
- c. C<sub>oss eff.</sub> is a fixed capacitance that gives the same charging time as C<sub>oss</sub> while V<sub>DS</sub> is rising from 0 % to 80 % V<sub>DS</sub>

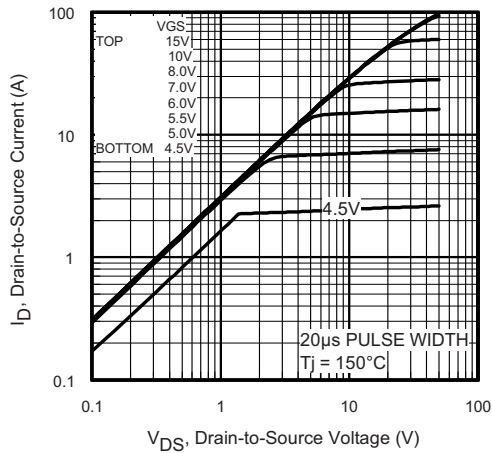
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



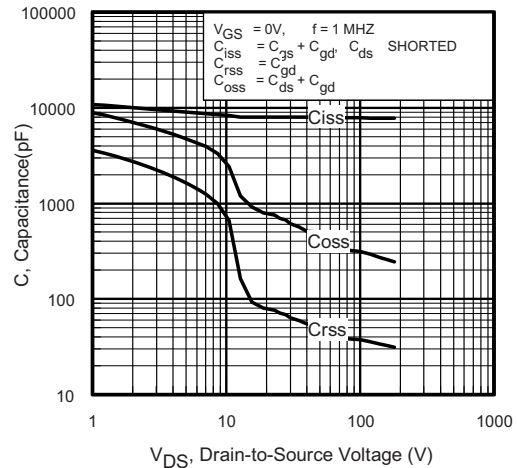
**Fig. 1 - Typical Output Characteristics**



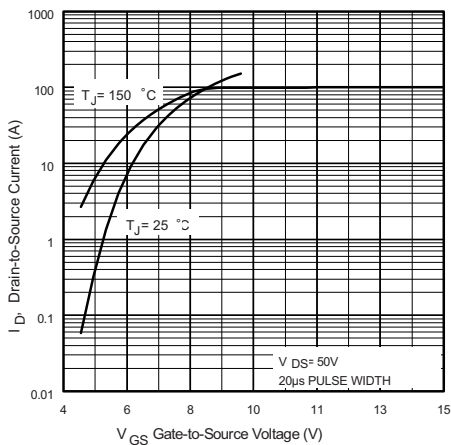
**Fig. 4 - Normalized On-Resistance vs. Temperature**



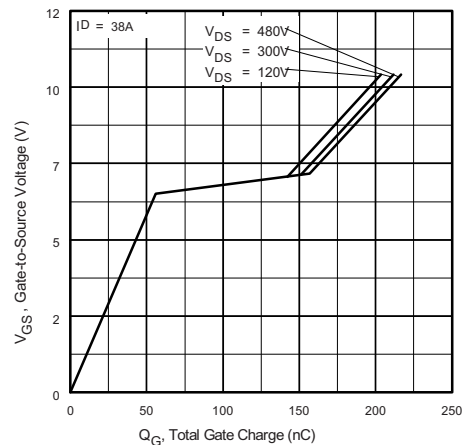
**Fig. 2 - Typical Output Characteristics**



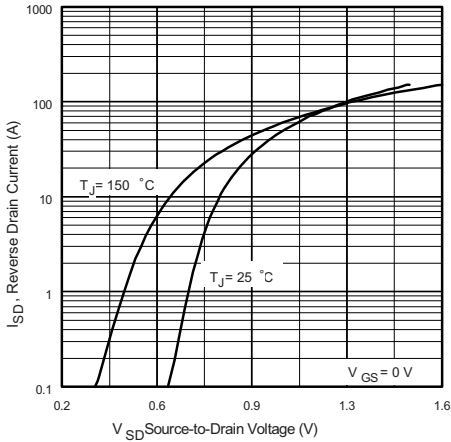
**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



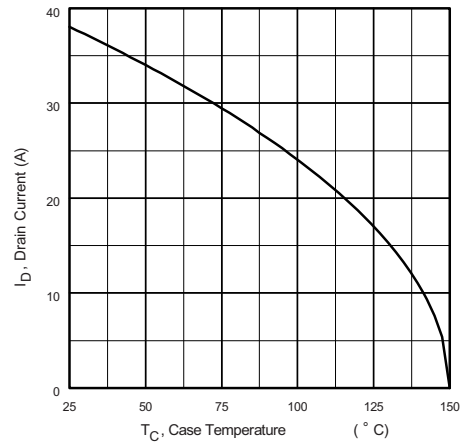
**Fig. 3 - Typical Transfer Characteristics**



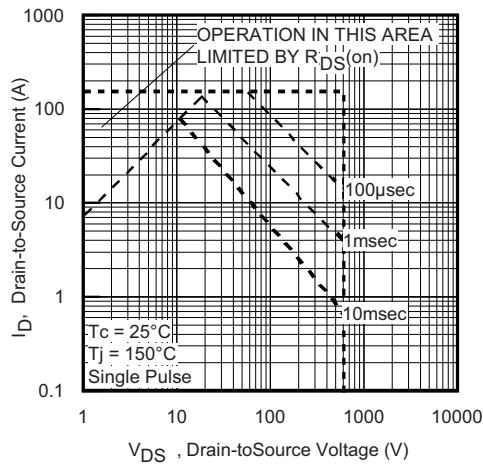
**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**



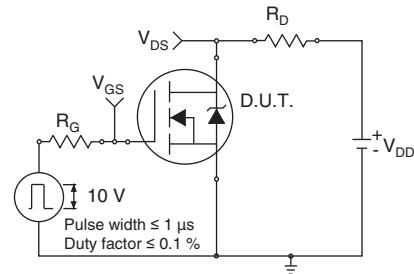
**Fig. 7 - Typical Source-Drain Diode Forward Voltage**



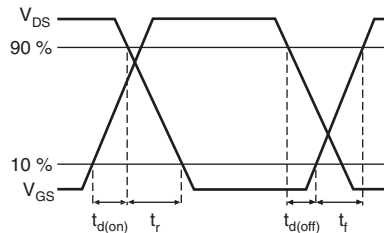
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



**Fig. 8 - Maximum Safe Operating Area**



**Fig. 10a - Switching Time Test Circuit**



**Fig. 10b - Switching Time Waveforms**

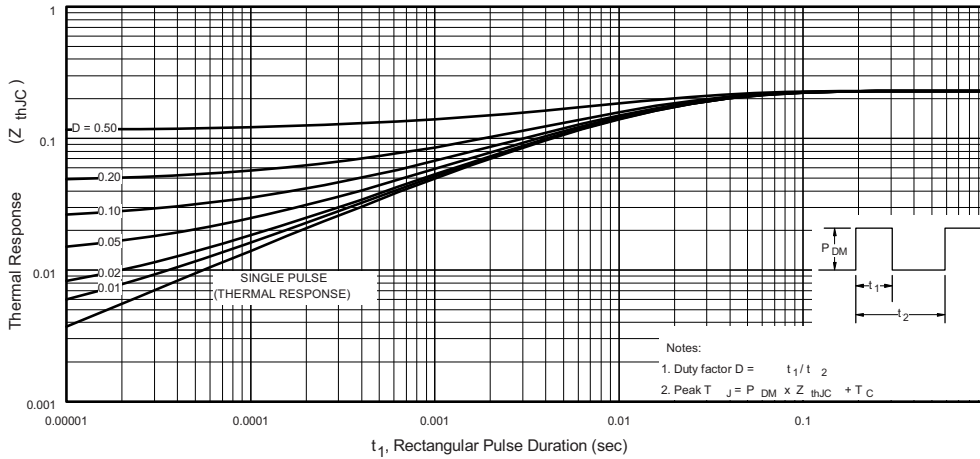


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

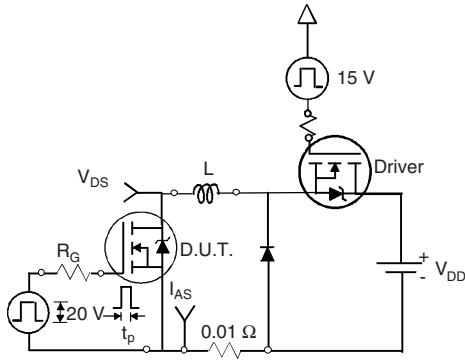


Fig. 12a - Unclamped Inductive Test Circuit

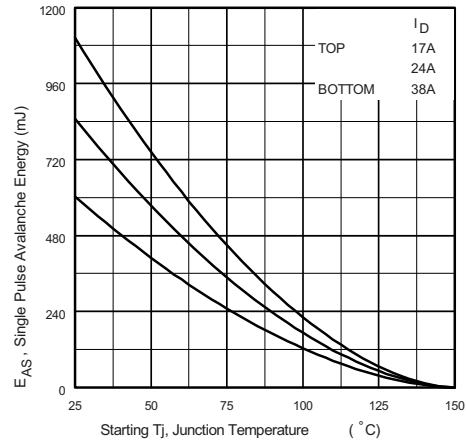


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

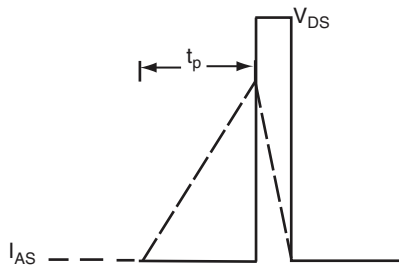


Fig. 12b - Unclamped Inductive Waveforms

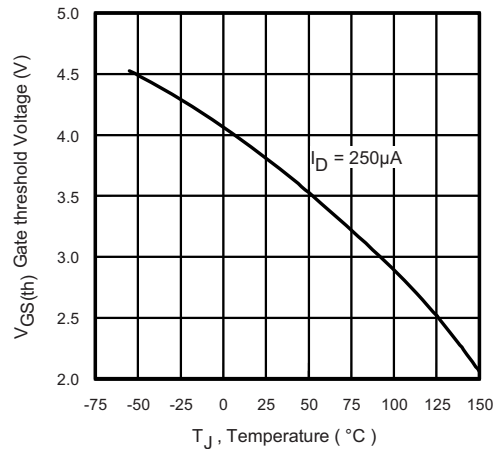


Fig. 12d - Threshold Voltage vs. Temperature

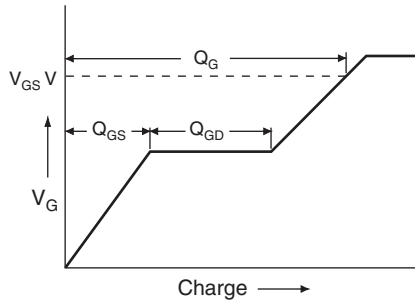


Fig. 13a - Basic Gate Charge Waveform

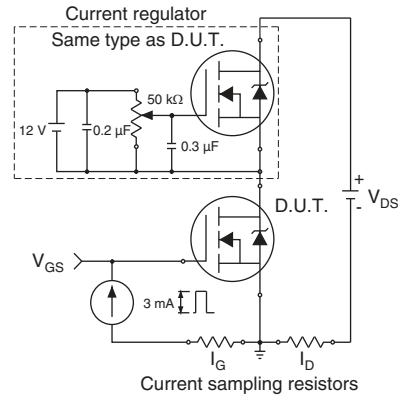
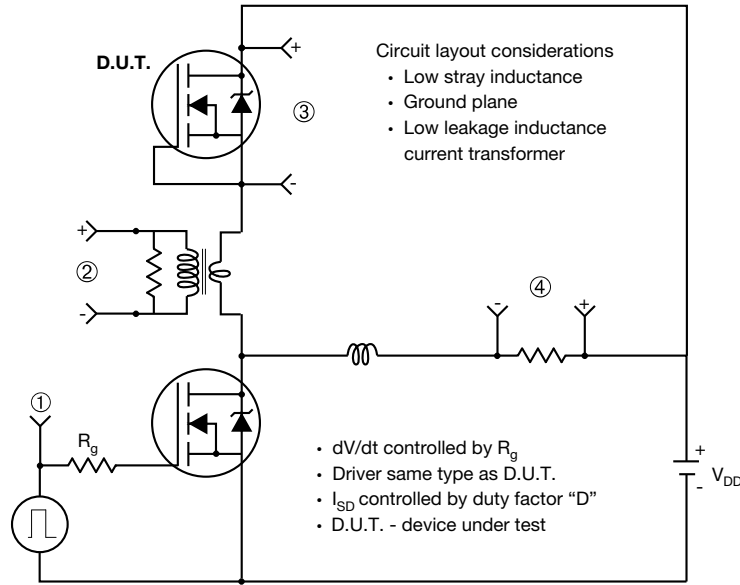


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



**Note**  
a.  $V_{GS} = 5\text{ V}$  for logic level devices

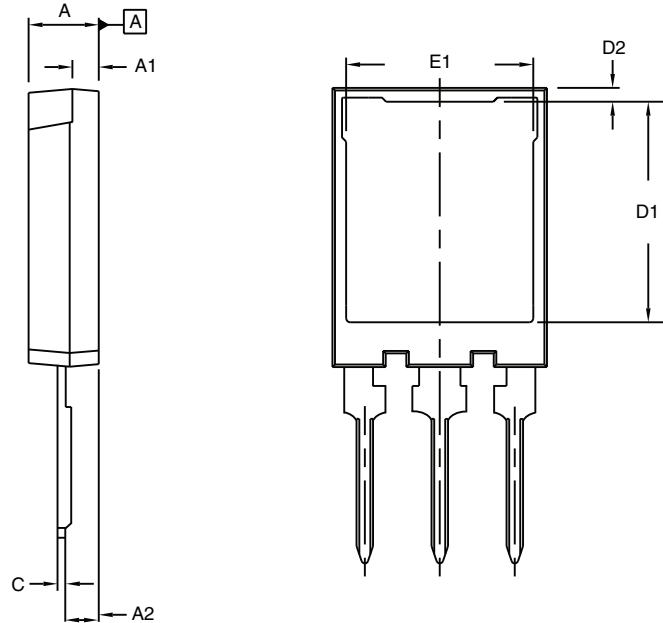
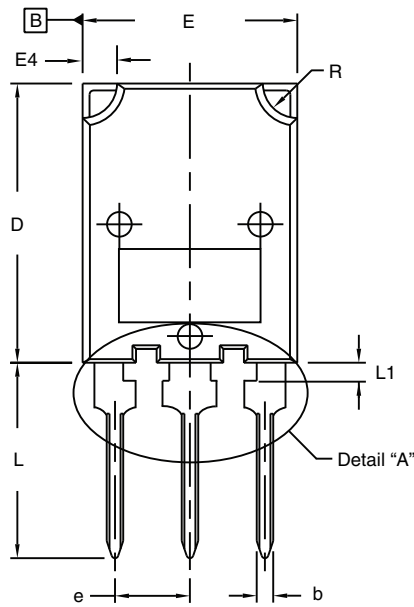
Fig. 14 - For N-Channel

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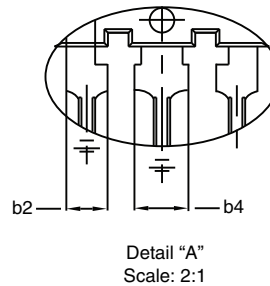


# TO-274AA (High Voltage)

## VERSION 1: FACILITY CODE = Y



⌀ 0.10 (0.25) Ⓜ B A Ⓜ



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.70	5.30	0.185	0.209
A1	1.50	2.50	0.059	0.098
A2	2.25	2.65	0.089	0.104
b	1.30	1.60	0.051	0.063
b2	1.80	2.20	0.071	0.087
b4	3.00	3.25	0.118	0.128
c <sup>(1)</sup>	0.38	0.89	0.015	0.035
D	19.80	20.80	0.780	0.819

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
D1	15.50	16.10	0.610	0.634
D2	0.70	1.30	0.028	0.051
E	15.10	16.10	0.594	0.634
E1	13.30	13.90	0.524	0.547
e	5.45 BSC		0.215 BSC	
L	13.70	14.70	0.539	0.579
L1	1.00	1.60	0.039	0.063
R	2.00	3.00	0.079	0.118

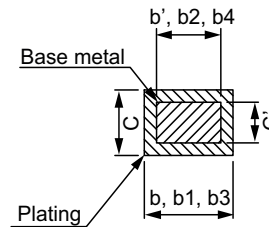
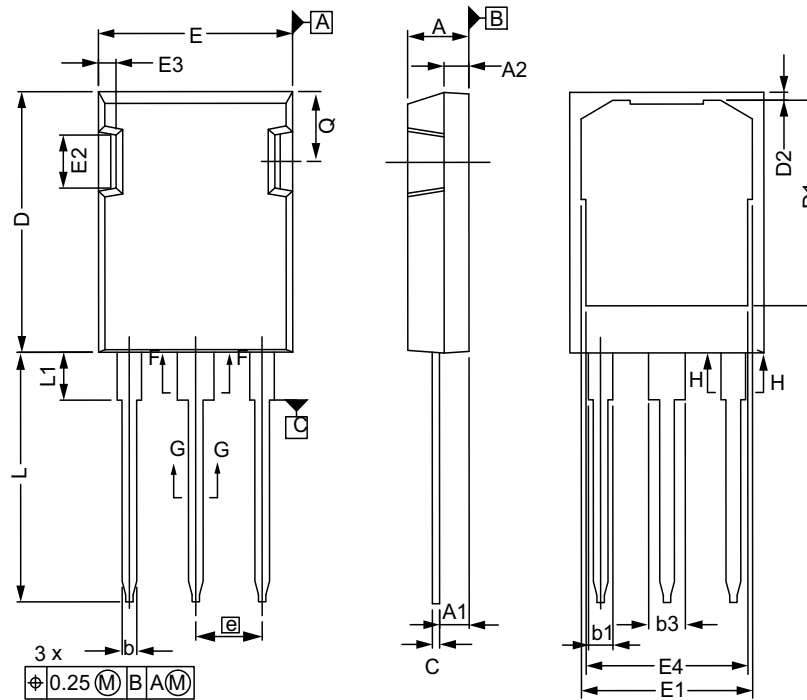
### Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outer extremes of the plastic body
- Outline conforms to JEDEC® outline to TO-274AA
- (1) Dimension measured at tip of lead





VERSION 2: FACILITY CODE = N



MILLIMETERS		
DIM.	MIN.	MAX.
A	4.83	5.21
A1	2.29	2.54
A2	1.91	2.16
b'	1.07	1.28
b	1.07	1.33
b1	1.91	2.41
b2	1.91	2.16
b3	2.87	3.38
b4	2.87	3.13
c'	0.55	0.65
c	0.55	0.68
D	20.80	21.10

MILLIMETERS		
DIM.	MIN.	MAX.
D1	16.25	17.65
D2	0.50	0.80
E	15.75	16.13
E1	13.10	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e	5.44 BSC	
N	3	
L	19.81	20.32
L1	3.70	4.00
Q	5.49	6.00

ECN: E20-0538-Rev. C, 19-Oct-2020  
DWG: 5975

Notes

- Dimensioning and tolerancing per ASME Y14.5M-1994
- Outline conforms to JEDEC® outline to TO-274AD
- Dimensions are measured in mm, angles are in degree
- Metal surfaces are tin plated, except area of cut



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